

# SOT1445-2

wafer level chip-scale package; 6 bumps; 0.69 mm x 0.44 mm  
x 0.29 mm

6 December 2016

Package information

## 1. Package summary

<b>Terminal position code</b>	B (bottom)
<b>Package type descriptive code</b>	WLCSP
<b>Package type industry code</b>	WLCSP6
<b>Package style descriptive code</b>	WLCSP (wafer level chip-size package)
<b>Mounting method type</b>	S (surface mount)
<b>Issue date</b>	6-12-2016
<b>Manufacturer package code</b>	SOT1445

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	0.675	-	0.69	0.705	mm
E	package width	0.425	-	0.44	0.455	mm
A	seated height	0.27	-	0.29	0.31	mm
A <sub>2</sub>	package height	0.185	-	0.2	0.215	mm
e	nominal pitch	-	-	0.25	-	mm
n <sub>2</sub>	actual quantity of termination	-	-	6	-	



## 2. Package outline

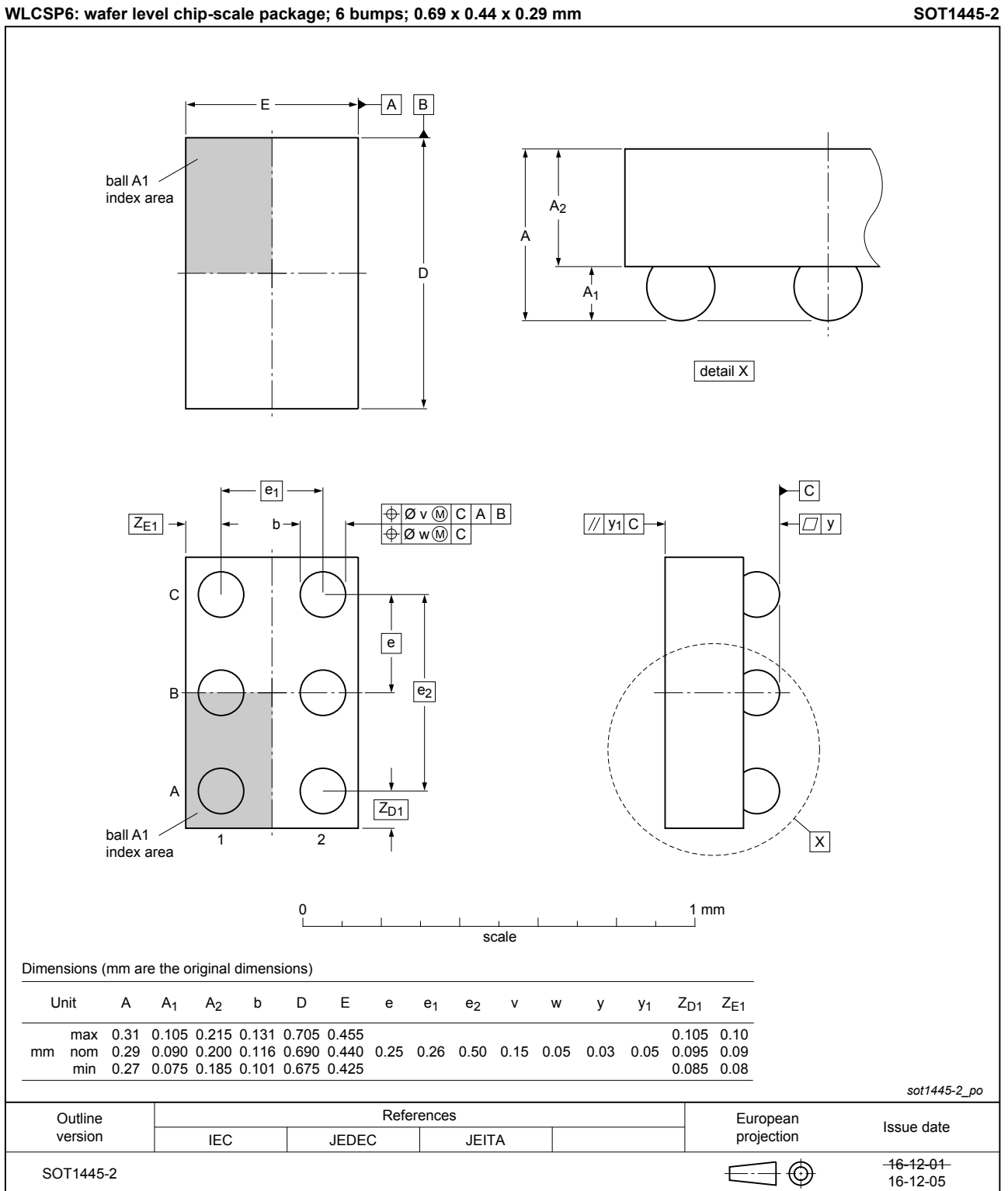


Fig. 1. Package outline WLCSP6 (SOT1445-2)

### 3. Legal information

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